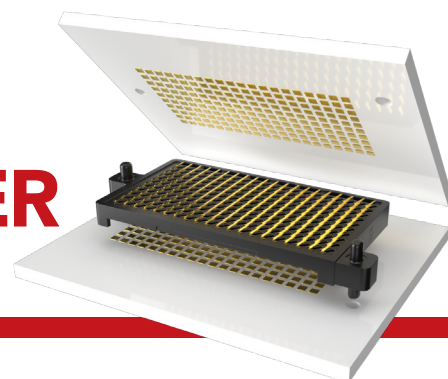


SUPERNOVA® LOW PROFILE COMPRESSION INTERPOSER

PAM4

56
Gbps



(1.00 mm) .0394" PITCH • GMI SERIES

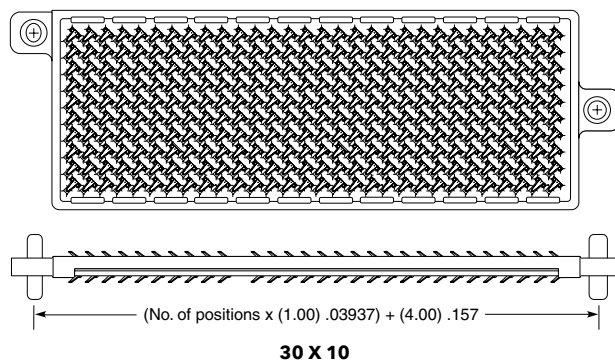
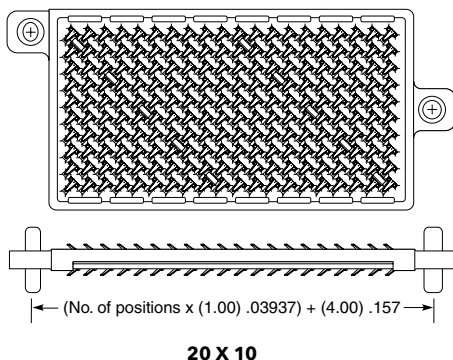
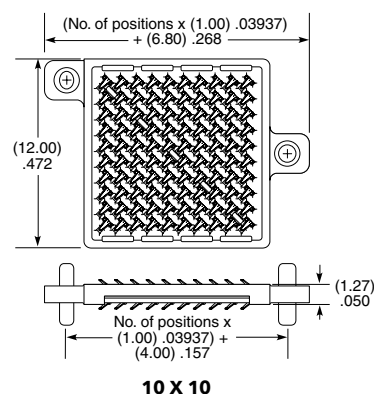
SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or 50 μ" (1.27 μm) Ni
Current Rating:
.9 A per pin
(10 pins powered)
Voltage Rating:
200 VAC/283 VDC

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Complanarity:
(0.05 mm) .002" (10-20)*
(0.08 mm) .003" (30)*
*(.004" stencil solution
may be available;
contact ipg@samtec.com)

GMI	POSITIONS PER ROW	STYLE	BOARD SPACING	PLATING OPTION	ROWS
	-10, -20, -30	-2 = Dual Compression	-1.27 = (1.27 mm) .050" Board Space	-G = 10 μ" (0.25 μm) Gold on contact area	-10 = Ten Rows



Note:
Some lengths, styles and
options are non-standard,
non-returnable